AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Previously Presented) A manufacturing method for a display which uses an organic EL element in a display portion, involving respectively preparing a circuit substrate with microstructures made with drive circuits for said organic EL element set at positions corresponding to pixels, a protective film made of an insulating material covering the microstructures, the protective film having through holes, and with wiring formed on the surface connecting to the microstructures through the through holes, and a transparent substrate with a transparent electrode layer common with the pixels laminated on the surface, and an emissive layer containing an organic EL layer and a cathode layer laminating on the upper surface of the transparent electrode layer at a position corresponding to said pixels, and then sticking together said circuit substrate and said transparent substrate with the side on which said wiring of said circuit substrate is formed and the side on which said cathode layer of said transparent substrate is formed facing towards the inside.

2. (Original) The manufacturing method for an organic EL display according to claim 1, the sticking together of said circuit substrate and said transparent substrate being performed by inserting an anisotropic conductive paste or an anisotropic conductive film therebetween.

3. (Original) The manufacturing method for an organic EL display according to claim 1, involving respectively preparing a roll of said circuit substrate, and a roll of said transparent substrate, and then unrolling said circuit substrate and said transparent substrate from these rolls while inserting an anisotropic conductive film therebetween, and pressing with a pressing roller from font and rear surfaces to thereby stick together said circuit substrate and said transparent substrate.

4. (Original) The manufacturing method for an organic EL display according to claim 3, after sticking together said circuit substrate and said transparent substrate, the stuck together product being cut to an optional length.

5. (Previously Presented) An organic EL display which uses an organic EL element in a display portion, microstructures made with drive circuits for said organic EL element being set at positions corresponding to pixels of a first substrate, a protective film made of an insulating material with through holes covering the microstructures, wiring passing through the through holes to connect to the microstructures, and an emissive layer containing an organic EL layer being formed on at least one of the first substrate and a second substrate and these first substrate and second substrate being stuck together.

6. (Previously Presented) An organic EL display which uses an organic EL element in a display portion, a circuit substrate with microstructures made with drive circuits for the organic EL element set at positions corresponding to pixels, a protective film made of an insulating material covering the microstructures, the protective film having through holes, and with wiring formed on the surface connecting to the microstructures through the through holes, and a transparent substrate with a transparent electrode layer common with the pixels laminated on the surface, and an emissive layer containing the organic EL layer and a cathode layer laminated on the upper surface of said transparent electrode layer at a position corresponding to said pixels, being stuck together with the side on which said wiring of said circuit substrate is formed and the side on which said cathode layer of said transparent substrate is formed facing towards the inside.

7. (Original) The organic EL display according to claim 6, said circuit substrate and said transparent substrate being stuck together by inserting an anisotropic conductive paste or an anisotropic conductive film therebetween.

8. (Previously Presented) A manufacturing method for an electro-optic device which uses electro-optic elements in a display portion, involving respectively preparing a first substrate with microstructures formed with drive circuits for said electro-optic elements set at positions corresponding to pixels, a protective film made of an insulating material with through holes covering the microstructures, wiring passing through the through holes to connect to the microstructures, and a second substrate with said electro-optic elements formed at positions corresponding to said pixels, and then sticking together said first substrate and said second substrate with the side of said first substrate on which said drive circuits are formed and the side of said second substrate on which said electro-optic elements are formed facing towards the inside.

9. (Previously Presented) An electro-optic device which uses electro-optic elements in a display portion, microstructures made with drive circuits for said electro-optic elements being set at positions corresponding to pixels of a first substrate, a protective film made of an insulating material with through holes covering the microstructures, wiring passing through the through holes for connecting to the microstructures, and an electro-optic layer being formed on at least one of said first substrate and a second substrate and said first substrate and second substrate being stuck together.

10. (Original) An electronic device provided with the electro-optic device according to claim 9.

11. (Previously Presented) A method of manufacturing a display using an organic EL element in a display portion comprising the steps of:

preparing a circuit substrate with drive circuits for the organic EL element set at positions corresponding to pixels;

covering the drive circuits with a protective film made of an insulating material, the protective film having a plurality of through holes;

connecting a plurality of wires to the drive circuits by passing the plurality of wires through the plurality of through holes;

preparing a transparent substrate, the transparent substrate including:

a transparent electrode layer common with the pixels laminated on the surface; and

an emissive layer containing an organic EL layer and a cathode layer laminated on the upper surface of the transparent electrode layer at a position corresponding to the pixels; and

joining the circuit substrate to the transparent substrate by connecting the plurality of wires of the circuit substrate to the cathode layer of the transparent substrate.

12. (Previously Presented) The method of Claim 11, wherein the drive circuits are included in microstructures.

13. (Previously Presented) The method of claim 11, wherein joining the circuit substrate to the transparent substrate further includes the step of inserting an anisotropic conductive paste between the circuit substrate and the transparent substrate.

14. (Previously Presented) The method of Claim 11, wherein joining the circuit substrate to the transparent substrate further includes the step of inserting an anisotropic conductive film between the circuit substrate and transparent substrate.

15. (Currently Amended) The method of Claim 11 further comprising the steps of:

rolling the circuit substrate into a circuit substrate roll;

rolling the transparent substrate into a transparent substrate roll;

unrolling the circuit substrate and the transparent substrate from the circuit and transparent substrate rolls;

inserting an anisotropic conductive film between the circuit substrate and the transparent substrate; and

pressing the circuit substrate and the transparent substrate together with a pressing roller, the pressing roller pressing the circuit substrate and the transparent substrate from front ~~font~~ to rear.

16. (Previously Presented) The method of Claim 15 further including the step of cutting the circuit substrate and the transparent substrate to an optional length.

17. (Previously Presented) An organic EL display using an organic EL element in a display portion comprising:

drive circuits formed on a first substrate for the organic EL element being set at positions corresponding to pixels;

a protective film formed from an insulating material with a plurality of through holes covering the drive circuits;

a plurality of wires passing through the plurality of through holes with a first end connecting to the drive circuits; and

an emissive layer containing an organic EL layer being formed on at least one of the first substrate and a second substrate, and the first substrate and second substrate being joined together.

18. (Previously Presented) The organic EL display of Claim 17 further comprising a plurality of microstructures, the drive circuits being included therein.

19. (Previously Presented) An organic EL display which uses an organic EL element in a display portion comprising:

a circuit substrate having a plurality of drive circuits for the organic EL element set at positions corresponding to a plurality of pixels;

a protective film made of an insulating material covering the drive circuits, the protective film having a plurality of through holes;

a plurality of wires connecting to the microstructures through the plurality of through holes;

a transparent substrate including:

a transparent electrode layer common with the pixels laminated on the surface; and

an emissive layer containing the organic EL layer; and

a cathode layer laminated on the upper surface of the transparent electrode layer at a position corresponding to the pixels, the plurality of wiring of the circuit substrate joining with the cathode layer of the transparent substrate.

20. (Previously Presented) The organic EL display of Claim 19 further comprising a plurality of microstructures, the drive circuits being included therein.

21. (Previously Presented) The organic EL display of Claim 19 wherein joining the circuit substrate to the transparent substrate includes inserting an anisotropic conductive paste between the circuit substrate and the transparent substrate.

22. (Previously Presented) The organic EL display of Claim 19 wherein joining the circuit substrate to the transparent substrate includes inserting an anisotropic conductive film between the circuit substrate and the transparent substrate.

23. (Currently Amended) A manufacturing method for an electro-optic device using electro-optic elements in a display portion comprising the steps of:

preparing a first substrate having drive circuits for the electro-optic elements set at positions corresponding to pixels;

covering the drive circuits with a protective film made of an insulating material with a plurality of through holes;

passing a plurality of wires through the plurality of through holes to connect to the drive circuits; ~~and~~

preparing a second substrate with the electro-optic elements formed at positions corresponding to the pixels; and

joining the first substrate and the second substrate such that the drive circuits of the first substrate and the electro-optic elements of the second substrate are placed between the first and second substrate.

24. (Previously Presented) The manufacturing method of Claim 23 further comprising a plurality of microstructures, the drive circuits being included therein.

25. (Previously Presented) An electro-optic device that uses electro-optic elements in a display portion comprising:

a plurality of drive circuits for the electro-optic elements being set at positions corresponding to pixels of a first substrate;

a protective film made of an insulating material with a plurality of through holes covering the drive circuits;

a plurality of wires passing through the plurality of through holes for connecting to the drive circuits; and

an electro-optic layer being formed on at least one of the first substrate and a second substrate and the first substrate and second substrate being joined together.

26. (Previously Presented) The electro-optic device of Claim 25 further comprising a plurality of microstructures, the drive circuits being included therein.

27. (Previously Presented) The electro-optic device of Claim 25 further comprising an electronic device.